

# N-Channel Enhancement-Mode Vertical DMOS FET

## **Features**

- · Free from Secondary Breakdown
- · Low Power Drive Requirement
- · Ease of Paralleling
- Low C<sub>ISS</sub> and Fast Switching Speeds
- · Excellent Thermal Stability
- · Integral Source-drain Diode
- · High Input Impedance and High Gain

## **Applications**

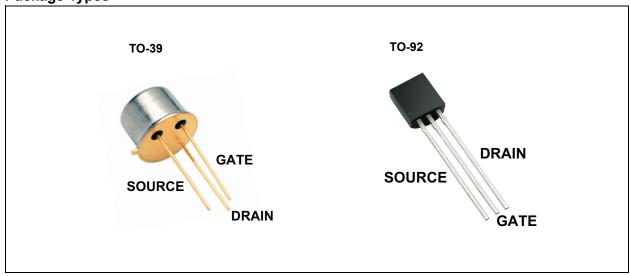
- · Motor Controls
- · Converters
- Amplifiers
- · Switches
- · Power Supply Circuits
- Drivers (Relays, Hammers, Solenoids, Lamps, Memory, Displays, Bipolar Transistors, etc.)

## **General Description**

VN2210 is an Enhancement-mode (normally-off) transistor that utilizes a vertical Double-diffused Metal-Oxide Semiconductor (DMOS) structure and a well-proven silicon gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors as well as the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally induced secondary breakdown.

Vertical DMOS Field-Effect Transistors (FETs) are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance and fast switching speeds are desired.

## **Package Types**



## 1.0 ELECTRICAL CHARACTERISTICS

## **Absolute Maximum Ratings †**

Drain-to-source Voltage	BV <sub>DSS</sub>
Drain-to-gate Voltage	BV <sub>DGS</sub>
Gate-to-source Voltage	
Operating and Storage Temperatures	

**† Notice:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

## **ELECTRICAL CHARACTERISTICS**

<b>Electrical Specifications</b> : T <sub>A</sub> = 25°C unless otherwise specified.								
Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions		
DC PARAMETERS (Note 1 unless oth	nerwise spe	ecified)						
Drain-to-source Breakdown Voltage	BV <sub>DSS</sub>	100	_	_	V	$V_{GS}$ = 0V, $I_D$ = 10 mA		
Gate Threshold Voltage	V <sub>GS(th)</sub>	8.0	_	2.4	V	$V_{GS} = V_{DS}$ , $I_D = 10 \text{ mA}$		
Change in V <sub>GS(th)</sub> with Temperature	$\Delta V_{GS(th)}$	1	-4.3	-5.5	mV/°C	$V_{GS} = V_{DS}, I_D = 10 \text{ mA (Note 2)}$		
Gate Body Leakage Current	I <sub>GSS</sub>	1	l	100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$		
		1	l	50	μΑ	$V_{GS}$ = 0V, $V_{DS}$ = Maximum rating		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	10	mA	$V_{DS}$ = 0.8 maximum rating, $V_{GS}$ = 0V, $T_A$ = 125°C (Note 2)		
ON Class Burin Control		3	4.5	_		V <sub>GS</sub> = 5V, V <sub>DS</sub> = 25V		
ON-State Drain Current	I <sub>D(ON)</sub>	8	17	_	Α	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 25V		
Static Drain-to-source ON-State Resis-	В	_	0.4	0.5	Ω	V <sub>GS</sub> = 5V, I <sub>D</sub> = 1A		
tance	R <sub>DS(ON)</sub>	_	0.27	0.35	12	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4A		
Change in R <sub>DS(ON)</sub> with Temperature	$\Delta R_{DS(ON)}$	_	0.85	1.2	%/°C	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4A (Note 2)		
AC PARAMETERS (Note 2)								
Forward Transconductance	G <sub>FS</sub>	1200	_		mmho	$V_{DS} = 25V, I_{D} = 2A$		
Input Capacitance	C <sub>ISS</sub>	_	300	500				
Common Source Output Capacitance	C <sub>OSS</sub>	_	125	200	pF	$V_{GS} = 0V, V_{DS} = 25V, f = 1 MHz$		
Reverse Transfer Capacitance	C <sub>RSS</sub>	1	50	65				
Turn-on Time	t <sub>d(ON)</sub>	_	10	15				
Rise Time	t <sub>r</sub>	_	10	15	ns	$V_{DD} = 25V, I_D = 2A,$		
Turn-off Time	t <sub>d(OFF)</sub>	1	50	65	113	$R_{GEN} = 10\Omega$		
Fall Time	t <sub>f</sub>	1	30	50				
DIODE PARAMETERS								
Diode Forward Voltage Drop	$V_{SD}$		1	1.6	<b>V</b>	$V_{GS} = 0V, I_{SD} = 4A$ (Note 1)		
Reverse Recovery Time	t <sub>rr</sub>	_	500	_	ns	$V_{GS} = 0V, I_{SD} = 1A $ (Note 2)		

Note 1: All DC parameters are 100% tested at 25°C unless otherwise stated. (Pulse test: 300 µs pulse, 2% duty cycle)

<sup>2:</sup> Specification is obtained by characterization and is not 100% tested.

# **TEMPERATURE SPECIFICATIONS**

<b>Electrical Characteristics:</b> Unless otherwise specified, for all specifications $T_A = T_J = +25$ °C.									
Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions			
TEMPERATURE RANGES									
Operating Temperature	T <sub>A</sub>	-55	_	+150	°C				
Storage Temperature	T <sub>S</sub>	-55	_	+150	°C				
PACKAGE THERMAL RESISTANCES									
TO-39	$\theta_{\sf JA}$		N/A	_	_				
TO-92	$\theta_{\sf JA}$		132	_	°C/W				

# THERMAL CHARACTERISTICS

Package	I <sub>D</sub> (Note 1) (Continuous) (A)	I <sub>D</sub> (Pulsed) (A)	Power Dissipation at T <sub>C</sub> = 25°C (W)	I <sub>DR</sub> (Note 1) (A)	I <sub>DRM</sub> (A)
TO-39	1.7	10	0.36	1.7	10
TO-92	1.2	8	0.74	1.2	8

**Note 1:** I<sub>D</sub> (continuous) is limited by maximum T<sub>j</sub>.

## 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore outside the warranted range.

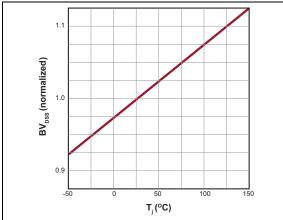


FIGURE 2-1: BV<sub>DSS</sub> Variation with Temperature.

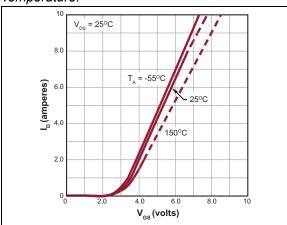


FIGURE 2-2: Transfer Characteristics.

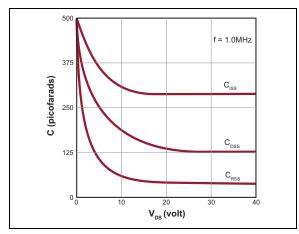


FIGURE 2-3: Capacitance vs. Drain-to-source Voltage.

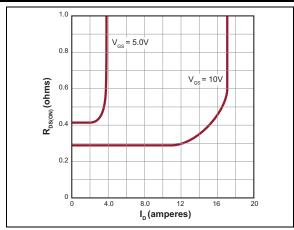
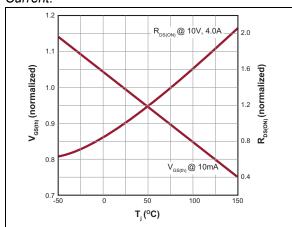


FIGURE 2-4: On-resistance vs. Drain Current.



**FIGURE 2-5:**  $V_{GS}$  and  $RV_{DS}$  Variation with Temperature.

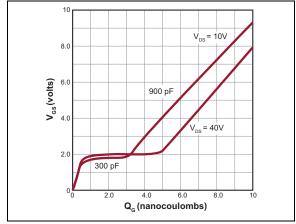


FIGURE 2-6: Gate Drive Dynamic Characteristics.

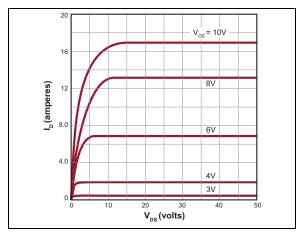
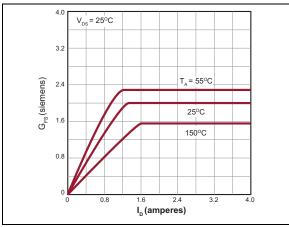
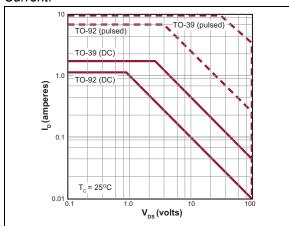


FIGURE 2-7: Output Characteristics.



**FIGURE 2-8:** Transconductance vs. Drain Current.



**FIGURE 2-9:** Maximum Rated Safe Operating Area.

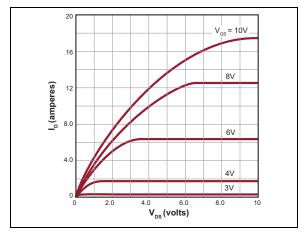
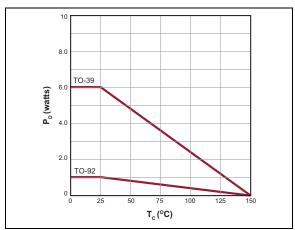


FIGURE 2-10: Saturation Characteristics.



**FIGURE 2-11:** Power Dissipation vs. Case Temperature.

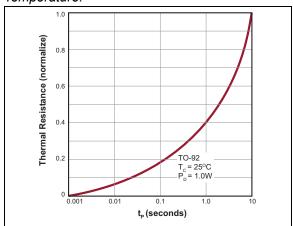


FIGURE 2-12: Thermal Response Characteristics.

# **VN2210**

## 3.0 PIN DESCRIPTION

Table 3-1 shows the description of pins in TO-39 and TO-92.

TABLE 3-1: TO-39/TO-92 PIN FUNCTION TABLE

Pin Number	TO-39	TO-92	Description
1	Source	Source	Source
2	Gate	Gate	Gate
3	Drain	Drain	Drain

## 4.0 FUNCTIONAL DESCRIPTION

Figure 4-1 illustrates the switching waveforms and test circuit for VN2210.

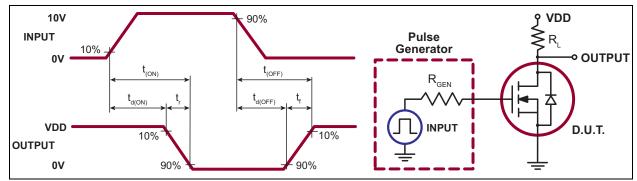


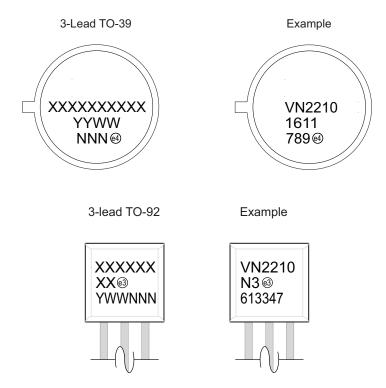
FIGURE 4-1: Switching Waveforms and Test Circuit.

# **PRODUCT SUMMARY**

BV <sub>DSS</sub> /BV <sub>DGS</sub> (V)	R <sub>DS(ON)</sub> (Maximum) (Ω)	V <sub>GS(th)</sub> (Maximum) (V)
100	0.35	2.4

## 5.0 PACKAGING INFORMATION

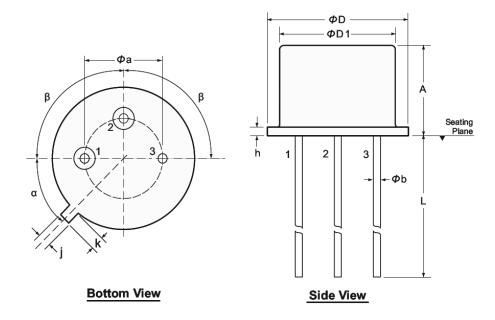
# **5.1 Package Marking Information**



Legend:	XXX	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	<b>e</b> 3	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3)
	<b>e</b> 4	can be found on the outer packaging for this package.  Pre-plated

**Note**: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

# 3-Lead TO-39 Package Outline (N2)

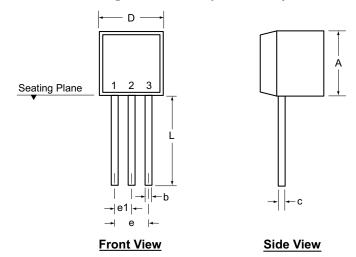


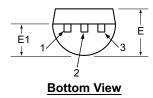
Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symbo	ol	α	β	Α	Фа	Φb	ΦD	<b>Φ</b> D1	h	j	k	L
	MIN			.240	.190	.016	.350	.315	.009	.028	.029	.500
Dimension (inches)	NOM	45° NOM	90° NOM	-	-	-	-	-	-	-	-	-
(	MAX		110111	.260	.210	.021	.370	.335	.125	.034	.040	.560*

JEDEC Registration TO-39.
\* This dimension is not specified in the JEDEC drawing.
Drawings not to scale.

# 3-Lead TO-92 Package Outline (L/LL/N3)





Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symb	ol	Α	b	С	D	E	E1	е	e1	L
	MIN	.170	.014 <sup>†</sup>	.014 <sup>†</sup>	.175	.125	.080	.095	.045	.500
Dimensions (inches)	NOM	-	-	-	-	-	-	-	-	-
(11101100)	MAX	.210	.022 <sup>†</sup>	.022 <sup>†</sup>	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.
\* This dimension is not specified in the JEDEC drawing.

<sup>†</sup> This dimension differs from the JEDEC drawing.

Drawings not to scale.

# **VN2210**

# APPENDIX A: REVISION HISTORY

# Revision A (June 2016)

- Converted Supertex Doc# DSFP-VN2210 to Microchip DS20005559A.
- Made minor text changes throughout the document.

# PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

XX		. x . x	Examples:	
Packa		T T	a) VN2210N2:	N-Channel Enhancement-Mode Vertical DMOS FET, 3-lead TO-39 Package, 500/Bag
VN2210	=	N-Channel Enhancement-Mode Vertical DMOS FET	b) VN2210N3-G:	N-Channel Enhancement-Mode Vertical DMOS FET, 3-lead TO-92 Package, 1000/Bag
N2	=	3-lead TO-39		
N3	=	3-lead TO-92		
G	=	Lead (Pb)-free/RoHS-compliant Package		
(blank)	=	500/Bag for N2 Package		
		1000/Bag for N3 Package		
does not in product.	clude	a "-G" designator. However, the package is an		
	VN2210  N2 N3  G (blank)	Package Options  VN2210 =  N2 =  N3 =  G =  (blank) =	Package Options  Environmental Media Type  VN2210 = N-Channel Enhancement-Mode Vertical DMOS FET  N2 = 3-lead TO-39 N3 = 3-lead TO-92  G = Lead (Pb)-free/RoHS-compliant Package  (blank) = 500/Bag for N2 Package 1000/Bag for N3 Package does not include a "-G" designator. However, the package is an	Package Options  Environmental Media Type  Options  N-Channel Enhancement-Mode Vertical DMOS FET  N2 = 3-lead TO-39 N3 = 3-lead TO-92  G = Lead (Pb)-free/RoHS-compliant Package  (blank) = 500/Bag for N2 Package

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